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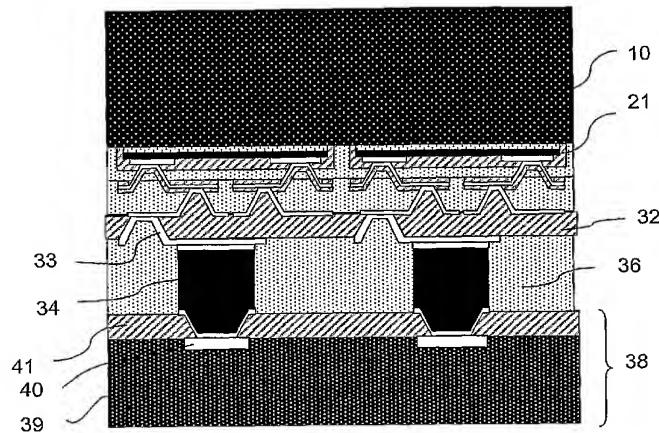
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(54) Title: DESIGN AND FABRICATION METHOD FOR MICROSENSOR



(57) Abstract: A method for fabricating a micro-sensor device comprising the steps of fabricating on a parent substrate (10) at least one sensor element (21); forming an interconnect layer (32) having first and second surfaces remote to the parent substrate (10) so as to enclose the at least one sensor element (21) between the first surface and the parent substrate; providing a plurality of electrical interconnections (33) between the at least one sensor element and a plurality of terminations at the second surface of the interconnect layer, said terminations adapted to interface with a readout substrate. The method may comprise the further step of providing a readout substrate (38) having a plurality of input connections (40) disposed on a first surface thereof, said input connections (40) arranged so as to substantially correspond with the terminations at the second surface of the interconnect layer, and interfacing the plurality of terminations with the corresponding input connections to form an integrated assembly.

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